

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [0736421200](#)
Status: **Active**
Overview: [hdm](#)
Description: 2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, Press-Fit, Open End, 144 Circuits

Documents:

3D Model	Product Specification PS-73670-9999 (PDF)
Test Summary (PDF)	RoHS Certificate of Compliance (PDF)
Drawing (PDF)	

Agency Certification

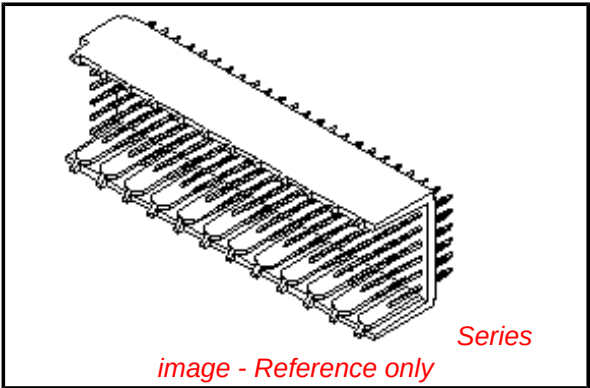
CSA	LR19980
UL	E29179

General

Product Family	Backplane Connectors
Series	73642
Application	Backplane
Comments	Standard Press-Fit
Component Type	PCB Header
Overview	hdm
Product Name	HDM®
Style	N/A

Physical

Circuits (Loaded)	144
Circuits (maximum)	144
Color - Resin	Black, Natural
Durability (mating cycles max)	250
First Mate / Last Break	No
Flammability	94V-0
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Phosphor Bronze
Material - Plating Mating	Gold
Material - Plating Termination	Gold
Material - Resin	High Temperature Thermoplastic
Number of Columns	24
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length (in)	0.138 In
PC Tail Length (mm)	3.50 mm
PCB Locator	No
PCB Retention	None
PCB Thickness Recommended (in)	0.062 In
PCB Thickness Recommended (mm)	1.60 mm
Packaging Type	Tube
Pitch - Mating Interface (in)	0.079 In
Pitch - Mating Interface (mm)	2.00 mm
Pitch - Term. Interface (in)	0.079 In
Pitch - Term. Interface (mm)	2.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.75
Plating min: Termination (µin)	2



EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
Contains SVHC: No
Halogen-Free
Status

China RoHS



**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of
Compliance, [click here](#)

Please visit the [Contact Us](#) section for any
non-product compliance questions.

Search Parts in this Series

[73642Series](#)

Mates With

[73632](#) HDM PLUS® Board-to-Board
Daughtercard Receptacle. [73780](#) HDM®
Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

*Tooling specifications and manuals are
found by selecting the products below.
Crimp Height Specifications are then
contained in the Application Tooling
Specification document.*

Global

Description	Product #
Flat Rock Tooling for Pneumatic Press	0622013700
HDM® Backplane Insertion Signal Contact Tool	0621001400
HDM® Backplane Insertion Head for 144 Positions	0622005703

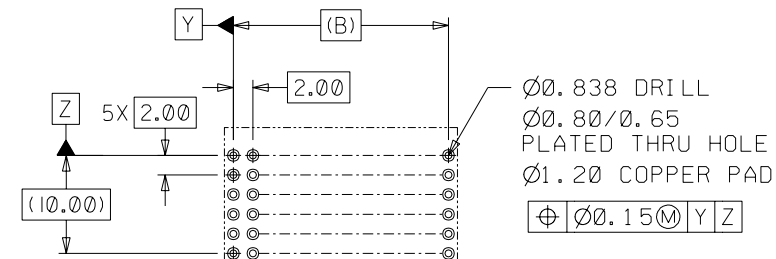
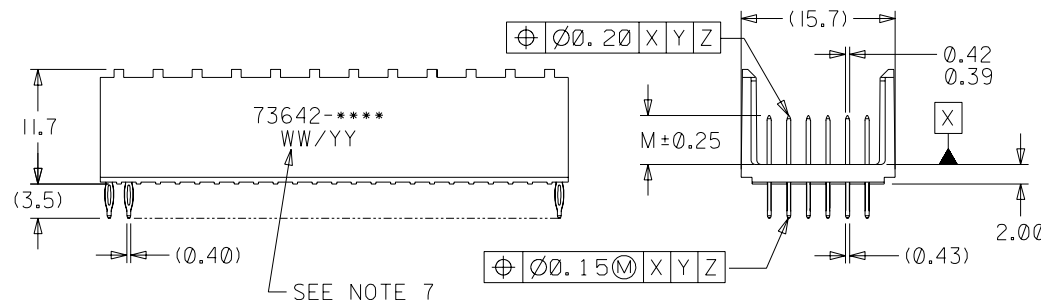
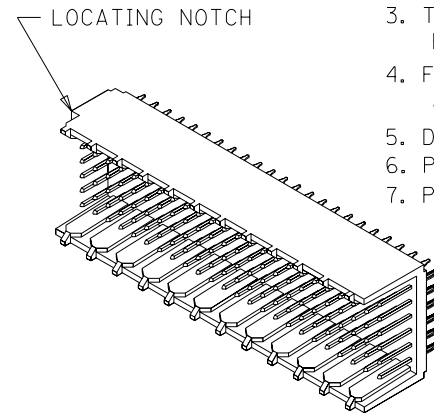
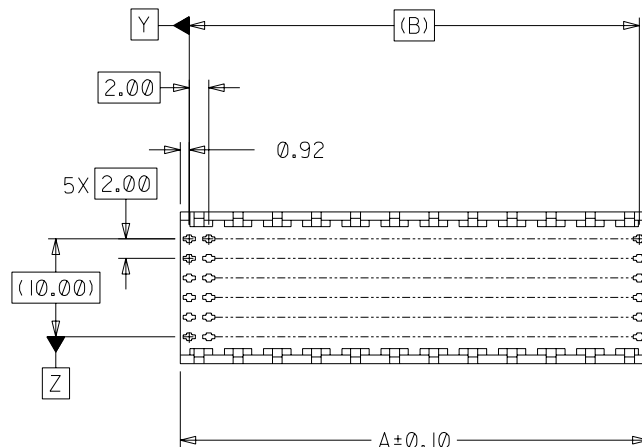
Plating min: Termination (µm)	0.05	Extraction Tool	0621001000
Polarized to PCB	No		
Stackable	Yes		
Surface Mount Compatible (SMC)	Yes		
Temperature Range - Operating	-55°C to +105°C		
Termination Interface: Style	Through Hole - Compliant Pin		
Electrical			
Current - Maximum per Contact	1A		
Data Rate	1.0 Gbps		
Real Signals (per 25mm)	75		
Shielded	No		
Voltage - Maximum	250V AC		
Material Info			
Reference - Drawing Numbers			
Packaging Specification	PK-70873-0818		
Product Specification	PS-73670-9999		
Sales Drawing	SDA-73642-****		
HDM and High Density Metric are trademarks of Amphenol Corporation			

This document was generated on 05/14/2010

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

NOTES:

1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED, UL94V-0, COLOR: BLACK, TERMINAL - PHOSPHOR BRONZE.
2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; NICKEL (Ni) AND GOLD FLASH OVERALL SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM THICKNESS; SELECTIVE TIN/LEAD (Sn/Pb) IN TAIL AREA; NICKEL (Ni) OVERALL.
3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION PS-73670-9999.
4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR AVAILABILITY.
5. DIMENSIONS ARE IN MILLIMETERS.
6. PACKAGE PER PK-70873-0818.
7. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE, APPROXIMATELY WHERE SHOWN.



PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN.

2	C
I	I
SH	REV

I	REVISED ECR UCP2003-2260 THOMAS 03/04/25	F	REVISED ECR UDT1999-0476 BINGHAM 98/12/21	C	REVISED PER ECR *U81357 BINGHAM 97/12/15
H	REVISED ECR UDT2000-0348 BINGHAM 99/10/12	E	REVISED ECR UDT1999-0243 BINGHAM 98/09/29	B	REVISED PER ECR *U70950 BINGHAM 97/02/14
G	REVISED ECR UDT1999-0662 BINGHAM 99/05/18	D	REVISED ECR UDT1998-0240 BINGHAM 98/05/06	A	RELEASED FOR PROD. PER ECR *U70371 BINGHAM 96/12/18
LTR.	REVISIONS	LTR.	REVISIONS	LTR.	REVISIONS

DIMENSIONS SHOWN (METRIC) INCH	
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°	
3 PLACE	± N/A
2 PLACE	± N/A
1 PLACE	± 0.10
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	
DRWG. BY	JRR
CHK'D. BY	SMR
APP'D. BY	CAB
SCALE	2 : 1

▽ = 0 ▼ = 0		REVISE ONLY ON CAD SYSTEM	
TITLE SALES ASSY, HDM BACKPLANE MODULE, OPEN END OPTION			
MOLEX INCORPORATED LITSE,ILL. 60532 U.S.A.		SHEET NO. 1 OF 2	DATE 96/12/18
PART NO. SEE SHEET 2		DRWG. NO. SDA-73642-****	
FILE NAME S73642X1		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	
DIV. DA		SIZE B	

	10	9	8	7	6	5	4	3	2	1	73642
F											
E											
D											
C											
B											
A											

MATERIAL NUMBER	NUMBER OF SIGNAL CONTACTS	PLATING	DIM "A"	DIM "B"	DIM "M"
73642-0000	72	SELECTIVE GOLD/GOLD FLASH	23.84	22.00	5.00
73642-0100	72	SELECTIVE GOLD/GOLD FLASH	23.84	22.00	5.50
73642-0200	72	SELECTIVE GOLD/GOLD FLASH	23.84	22.00	6.00
73642-1000	144	SELECTIVE GOLD/GOLD FLASH	47.84	46.00	5.00
73642-1100	144	SELECTIVE GOLD/GOLD FLASH	47.84	46.00	5.50
73642-1200	144	SELECTIVE GOLD/GOLD FLASH	47.84	46.00	6.00
73642-2000	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	23.84	22.00	5.00
73642-2100	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	23.84	22.00	5.50
73642-2200	72	SELECTIVE GOLD/SELECTIVE TIN-LEAD	23.84	22.00	6.00
73642-3000	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	47.84	46.00	5.00
73642-3100	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	47.84	46.00	5.50
73642-3200	144	SELECTIVE GOLD/SELECTIVE TIN-LEAD	47.84	46.00	6.00

		C	SEE SHEET I
LTR.	REVISIONS	LTR.	REVISIONS

DIMENSIONS SHOWN (METRIC) INCH			
UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°			
INCH		METRIC	
3 PLACE	± N/A	---	
2 PLACE	± N/A	± 0.05	
1 PLACE	---	± 0.10	
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			
DRWG. BY JRR	CHK'D. BY SMR		
APP'D. BY CAB	SCALE NO*NE		

▽ = 0		▼ = 0		REVISE ONLY ON CAD SYSTEM	
TITLE					
SALES ASSY, HDM BACKPLANE MODULE, OPEN END OPTION					
MOLEX INCORPORATED		SHEET NO.		DATE	
LISLE,ILL. 60532 U.S.A.		2		97/12/15	
PART NO.		DRWG. NO.			
SEE CHART		SDA-73642-*****			
FILE NAME		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.			DIV.
S73642X2					DA
DGN					B



**Стандарт
Электрон
Связь**

Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию .

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России , а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

Минимальные сроки поставки, гибкие цены, неограниченный ассортимент и индивидуальный подход к клиентам являются основой для выстраивания долгосрочного и эффективного сотрудничества с предприятиями радиоэлектронной промышленности, предприятиями ВПК и научно-исследовательскими институтами России.

С нами вы становитесь еще успешнее!

Наши контакты:

Телефон: +7 812 627 14 35

Электронная почта: sales@st-electron.ru

Адрес: 198099, Санкт-Петербург,
Промышленная ул, дом № 19, литера Н,
помещение 100-Н Офис 331